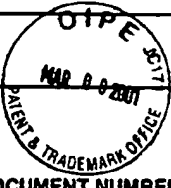


FORM PTO-1449
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2813

U.S. PATENT DOCUMENTS

EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPRO- PRIATE

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANS- LATION
					YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

VB		Gary Shade and Kendall Scott Wills, <i>Photoemission Microscopy</i> , 1997 ASM International, pp. 181-182.
VB		B. Bossmann, P. Baurechmidt, K. Hussey, and E. Black, <i>Failure Analysis Techniques with the Confocal Laser Scanning Microscope</i> , ISTFA '92: The 18 th International Symposium for Testing & Failure Analysis, October 1992, pp. 351-361.
		Nevil M. Wu, Kevin Weaver, James H. Lin, <i>Failure Analysis from Back Side of Die</i> , ISTFA '96: 22 nd International Symposium for Testing and Failure Analysis, November 1996, 7 pages.
		TW. Joseph, A.L. Berry, B. Bossman, <i>Infrared Laser Microscopy of Structures on Heavily Doped Silicon</i> , ISTFA '92: The 18 th International Symposium for Testing & Failure Analysis, October 1992, pp. 1-7.
		D.L. Barton, P. Tangyunyong, J.M. Soden, A.Y. Liang, F.J. Low, A.N. Zaptatin, K. Shivanandan, and G. Donohoe, <i>Infrared Light Emission from Semiconductor Devices</i> , Proceedings of the 22 nd International Symposium for Testing and Failure Analysis, November 1996, pp. 9-17.
		Chun-Cheng Tsao, Steven, Kasapi, and Kurt Hurley, <i>Backside waveform probing of CMOS devices using infrared laser at wavelength of 1064 nm</i> , 6 pages.
		C. Chiang, N. Khurana, D.T. Hurley, and K. Teasdale, <i>Backside Emission Microscopy for Integrated Circuits on Heavily Doped Substrate</i> , Proceedings from the 24 th International Symposium for Testing and Failure Analysis, November 1998, pp. 447-453.
		Kendall Scott Wills, Terri Lewis, Greg Bilus, Hai Hoang, <i>Optical Beam Induced Current Applications for Failure Analysis of VLSI Devices</i> , 1997 ASM International, pp. 21-26.
		Yeoh Eng Hong and Martin Tay Tiong We, <i>The application of novel Failure Analysis Techniques for Advanced Multi-Layered CMOS devices</i> , 6 pages.
		T. Koyama, Y. Meshiko, M. Sekine, H. Koyama and K. Horie, <i>New non-bias optical beam induced current (NB-OBIC) techniques for evaluation of Al interconnects</i> , 1995 IEEE, pp. 228-233.
		Said F. Al-sarawi, <i>Tape-Automated Bonding</i> , Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, pp. 1-2.
		Said F. Al-sarawi, <i>Solder Bump Bonding</i> , Centre for High Performance Integrated Technologies and Systems (CHIPTEC), March 1997, 1 page.

EXAMINER

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